

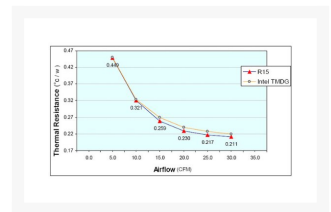
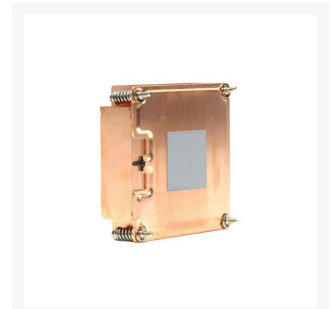


 DYNATRON

Dynatron R15 Intel Socket 2011 1U Vapor Chamber Heatsink

Special Price
\$36.74 was
\$48.99

Product Images



Short Description

Constructed from copper for optimal heat transfer and sporting vapor chamber technology, the R15 supports a CPU with maximum TDP rating of 150W. Thermal compound is pre-printed with Shin-Etsu G751; no

additional thermal compound is required. The R15 passive heatsink is designed to be used in conjunction with an active cooling system; the 1U case must have active cooling, e.g., fans.

Description

Passive 1U rackmount CPU cooler from Dynatron® for Intel® LGA 2011 (Socket R) Sandy Bridge server processors.

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What is a Vapor Chamber and how does that help me? A vapor chamber is, in essence, a flattened heatpipe in direct contact to the CPU surface that transfers and dissipates heat more efficiently than a traditional heatsink can manage. The vapor chamber is air tight, containing a coolant, and operates through a continuous cycle of evaporative cooling. What this provides you with is more effective cooling and CPU thermal protection with no additional bulk.

Features

- Solid copper heatsink with stacked-fins
- CPU Support: LGA 2011 (Socket R), Sandy Bridge - EP/EX, Intel® Core™ i7, Xeon® E5 and other LGA 2011 processors, 150W TDP MAX
- Supports 1U+
- Shin-Etsu G751 Thermal Compound (pre-printed)
- Dimensions: 90 x 90 x 27mm, 3.54" x 3.54" x 1.06" (in inches)
- RoHS Compliance

Specifications

CPU Socket 2011



CPU Support Intel® Sandy Bridge EP/EX Processors



Solution 1U Server



Overall Dimension 90.0 x 90.0 x 27.0 mm



Weight 435 g



Material Vapor chamber base with Copper stacked fin



Thermal Resistance VS. Cooling Fan Speed



Note

1. Support CPU Power up to 150 Watts
2. Thermal Grease Pre-Printed with Shin-Etsu G751
3. RoHS Compliance
4. Backplate is not included.

Additional Information

Brand	Dynatron
SKU	R15
Weight	1.5000
Compatibilty	Intel LGA 2011&(-3)/2066
Material	Copper
Special Price	\$36.74

